SIKA e-SiC® 3.5N 70F
Product information

High-purity silicon carbide powder for semiconductor and electronic applications

High-purity silicon carbide, manufactured using the Acheson process, is utilized in the semiconductor industry for a wide range of components and devices, including wafer boats, paddles, tubes, flanges, and more.

Typical chemistry

Char. description	Unit	Value
Free C	%	0,02
Free Si	%	0,07
Total O_2	%	0,05
Al	ppm	110
Fe	ppm	100
Ni	ppm	25
V	ppm	33
Ti	ppm	7,5
B	ppm	1,2
Cr	ppm	<0,3
Cu	ppm	0,16
S	ppm	2,1
Zn	ppm	1
Li	ppm	<0,05

Particle size distribution – laser technique

Char. description	Unit	Value
d10%	µm	312
d50%	µm	226
d90%	µm	164

Analytical procedures:

All measurement is in accordance to FEPA, ANSI or JIS, or other methods in agreement with customers.
Trace element analysis by GDMS

Packaging:

25 kg paper bags